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**Application No.: 10/017,805** 

Docket No.: JCLA7245

**In The Claims:** 

1. (Currently Amended) A photoresist with an adjustable to a polarized light response

suitable for use in a photolithography process, the photoresist comprising:

a photosensitive polymer, wherein: the photosensitive polymer absorbs an exposure light

source to generate an optical reaction in the photolithography process; the photosensitive

polymer is oriented to a specific direction by a physical method; and under an electromagnetic

field, and the photosensitive polymer comprises a photosensitive section for absorbing an

exposure light to generate an optical reaction and an anti-etching section for increasing a resist

force against a plasma etching, and the photosensitive polymer is able has a response to a

polarized light, wherein the response varies as according to an angle variation between the

specific direction and a polarization direction of the polarized light changes.

2. (Original) The photoresist according to claim 1, wherein the linear photosensitive

polymer includes a linear photosensitive polymer.

3. (Original) The photoresist according to claim 2, wherein when a direction of the linear

photosensitive polymer is parallel to the polarization direction of the polarized light, the liner

photosensitive polymer has a maximum polarized light response, and when the direction of the

linear photosensitive polymer is perpendicular to the polarization direction of the polarized light,

the liner photosensitive polymer has a minimum polarized light response.

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Claim 4. (canceled)

5. (Currently Amended) The photoresist according to claim 14, wherein the

photosensitive section includes a PMDA.

6. (Currently Amended) The photoresist according to claim 14, wherein the

photosensitive section has a molecule weight of  $10^2 \sim 10^8$ .

7. (Currently Amended) The photoresist according to claim 14, wherein the anti-etching

section includes ODA.

8. (Currently Amended) The photoresist according to claim 14, wherein the

photosensitive section has a molecule weight as  $10^2 \sim 10^8$ .

9. (Currently Amended) The photoresist according to claim 1, wherein the physical

method electromagnetic field is includes applying an electric field and when the photosensitive

polymer has electric dipoles.

10. (Currently Amended) The photoresist according to claim 9, wherein applying the an

electric field includes using a plasma.

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11. (Currently Amended) The photoresist according to claim 9, wherein applying the an electric field includes using a polarized ultra-violet light.

- 12. (Currently Amended) The photoresist according to claim 9, wherein applying the an electric field includes using a microwave.
- 13. (Currently Amended) The photoresist according to claim 1, wherein the physical method-electromagnetic field is includes applying a magnetic field and when the photosensitive polymer has magnetic dipoles.
- 14. (Currently Amended) The photoresist according to claim 139, wherein applying the a magnetic field includes using a plasma.